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Enhanced electromechanical coupling coefficient and performance of AlScN/Si surface acoustic wave devices by scandium doping

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Abstract: This paper reports characterization of scandium aluminum nitride ($\text{Al}_{1-x}\text{Sc}_x\text{N}$, $x = 27\%$) films and its based surface acoustic wave (SAW) devices. Both AlScN and AlN films were deposited on silicon by sputtering and possessed columnar microstructures with (0002) crystal orientation. The AlScN/Si SAW devices showed an improved electromechanical coefficients (K^2 , $\sim 2\%$) compared with those of pure AlN films ($< 0.5\%$). The performance of the two types of devices, with acoustofluidic as an example, is also investigated and compared. Much lower threshold powers for both acoustic streaming and pumping of water droplets are achieved for the AlScN/Si SAW devices, acoustic streaming velocity is doubled and the pumping velocity is tripled compared with those using the AlN/Si SAW devices. Mechanical characterization shows that Young's modulus and hardness of the AlN film decrease significantly when Sc is doped, and is responsible for the decreased acoustic velocity, resonant frequency and increased temperature coefficient of frequency of the AlScN SAW devices.

Key word: AlScN, surface acoustic wave, microfluidics.

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1. Instruction

It is well reported that surface acoustic wave (SAW) devices can be utilized to fabricate sensors, actuator, and microfluidics and lab-on-chip systems with functions of sensing, actuating, streaming, pumping, jetting, particle manipulation and nebulization *etc.*¹⁻⁷ Most of these SAW devices were made on bulk piezoelectric materials such as LiNbO_3 due to their good performance.^{5,7} However, the relatively brittle nature and high cost of substrate materials, as well as difficulty in integration with

CMOS process could limit their applications. Thin film acoustic waves based on piezoelectric thin film materials, such as zinc oxide (ZnO) and aluminum nitride (AlN), are considered to be the future technology for the acoustic wave based sensors, microfluidics and lab-on-chips.^{3,6,8,9} Using thin films, rather than expensive bulk materials, it is convenient to integrate microelectronics and multiple sensing or microfluidics techniques into a lab-on-chip with low cost and multiple functions on various substrates (*e.g.* silicon, glass, metal, or polymer).^{7,10-13}

Currently, piezoelectric thin films such as ZnO have been extensively explored for SAW based sensors and microfluidics.^{6,7,14} AlN, another extensively used piezoelectric film materials in micro-electro mechanical system (MEMS), has great advantages such as high acoustic velocity, outstanding stability at high temperatures, excellent chemical inertness and good compatibility with CMOS process.¹⁵ It is one of the most important piezoelectric materials for many applications including energy harvesting,¹⁶ MEMS,¹⁷ sensors^{18,19} and acoustic wave devices, *etc.*^{8,20,21} Currently AlN based SAW devices and film bulk acoustic resonator (FBAR) devices have been widely explored for sensors and actuators applications.²² However, its relatively low electromechanical coupling coefficient (K^2) compared with those of the other materials (*e.g.*, LiNbO₃, PZT, ZnO *etc.*) limits its successful applications in sensor, actuator and microfluidics.^{20,23-25}

Recently, it was reported that AlScN alloy with a high concentration of scandium (Sc) can significantly improve its piezoelectric properties.²⁶⁻²⁸ Akiyama *et al.* reported that AlScN with 43% Sc showed an increase of piezoelectric moduli (d_{33}) by over 400%.²⁶ Based on *ab initio* simulation, Tasnádi *et al.* revealed that the increase of cell volume causes the elastic softening and rise of d_{33} values.^{27,28} Using 46% Sc-alloyed AlN, Hashimoto *et al.* fabricated Sezawa mode SAW devices on AlScN/SiC substrate and demonstrated that its value of electromechanical coefficients can be increased up to 4%.²⁹ In our previous work, K^2 value for the Rayleigh SAW mode can be enhanced more than 300% when applying a 27% Sc element in AlScN.^{30,31} The significant improvement of K^2 value can be expected to lead to a higher efficiency for sensing, actuation and microfluidic applications, which will provide a promising opportunity for making better integrated lab-on-a-chips.

Current research on this topic has been focused on the understanding of physical mechanisms of scandium doping and enhancement of piezoelectric property, with few in-depth exploration for applications in sensors, actuators and microfluidics. In this study, we characterize the film properties and K^2 value and explore application of the AlScN thin film based SAW devices, with main focus on microfluidics, and compare with those from the AlN based SAW microfluidics.

Doping of Sc in AlN would affect the mechanical strength of the films, consequently the integrity, reliability and stability of micro-devices for long-term application. However it is not clear whether the change of the mechanical strength by Sc-doping would affect the properties of the AlScN SAW devices. Here we also report the characterization of the mechanical properties of the films by nanoindentation,

and the effect on SAW devices of the Sc-alloyed AlN film which can provide valuable guidelines for optimizing the design of coatings on the devices.³²

2. Material and methods

Thin films of AlScN and AlN were deposited on Si (100) substrate with a thickness of $\sim 3 \mu\text{m}$ using DC reactive sputtering. AlScN thin films were deposited with a ScAl alloy target at a plasma power of 400 W and a base pressure in the deposition chamber of ~ 0.25 Pa without external substrate heating. AlN films were deposited using an Al target with nitrogen gas pressure of ~ 0.2 Pa, and the plasma power was set to be 800 W. Detailed deposition conditions were reported in our previous work.^{31,33,34} Post annealing of the films were performed at $800 \text{ }^\circ\text{C}$ with a duration of 10 min, under nitrogen protection with a N_2 gas flow rate of 1 L/min.

Scanning electron microscope (SEM, Hitachi SU70, Japan) and atomic force microscope (AFM, SPI-3800N, Seiko Co., Japan) were used to characterize thin film microstructure and morphology. X-ray photoelectron spectroscopy (XPS, K-Alpha, Thermo Scientific, UK) was performed using a monochromatic Al $\text{K}\alpha$ X-ray source (1486.6 eV, 36 W) with an X-ray voltage of 12 kV.

Nanoindentation tests were performed using a Hysitron Triboindenter (Hysitron Inc. Nanomechanical Test Instruments, Minneapolis, MN, USA) with a Berkovich indenter. Displacement control protocol was adopted to investigate the depth-dependent properties. In this protocol, the loading and unloading rates were 15 nm/s, and the maximum penetration depth was increased from 15 nm to 100 nm. For each test, at least 10 indentations were performed and the average readings of elastic modulus and hardness were obtained using the Oliver and Pharr method.³⁵

SAW devices were fabricated on these thin film samples and the Ti/Au (5 and 60 nm thickness, respectively) interdigital transducers (IDT) were fabricated using a standard photolithograph and lift-off process. The wavelength of the devices was set to be $20 \mu\text{m}$, with a delay line of 20λ . Characterization of frequencies of the SAW devices was conducted using a network analyzer (Agilent E5071C).³¹

For microfluidic tests, a signal generator (Marconi 2024) and a power amplifier (Amplifier research, 75A250) were utilized to generate and amplify the RF signals before applied to the SAW device, which was put on a bulk Al holder for easy heat dissipation. The movement of fluidic streaming was captured using a video camera. For microfluidic experiments, a hydrophobic layer of CYTOP (Asahi Glass Co. Ltd.) with ~ 200 nm thickness was deposited on the SAW devices. Water droplets of $2 \mu\text{L}$ were used, which was put about 2 mm in front of IDTs. The temperature coefficients of frequency (TCF) were measured in the temperature range of $30 \text{ }^\circ\text{C}$ to $90 \text{ }^\circ\text{C}$ for both the AlN and AlScN SAW devices.

3. Results and discussions

XPS survey scans of both the AlN and AlScN thin films are shown in Fig. 1(a). Carbon peak appears at ~ 284.6 eV, which is due to the carbon contamination from the air and residual gaseous carbon-species in sputter chamber. The strong O 1s peaks of both the samples are linked to the residual oxygen in the gas atmosphere during sputtering and air contamination. The N 1s peak is positioned at ~ 396.8 eV.

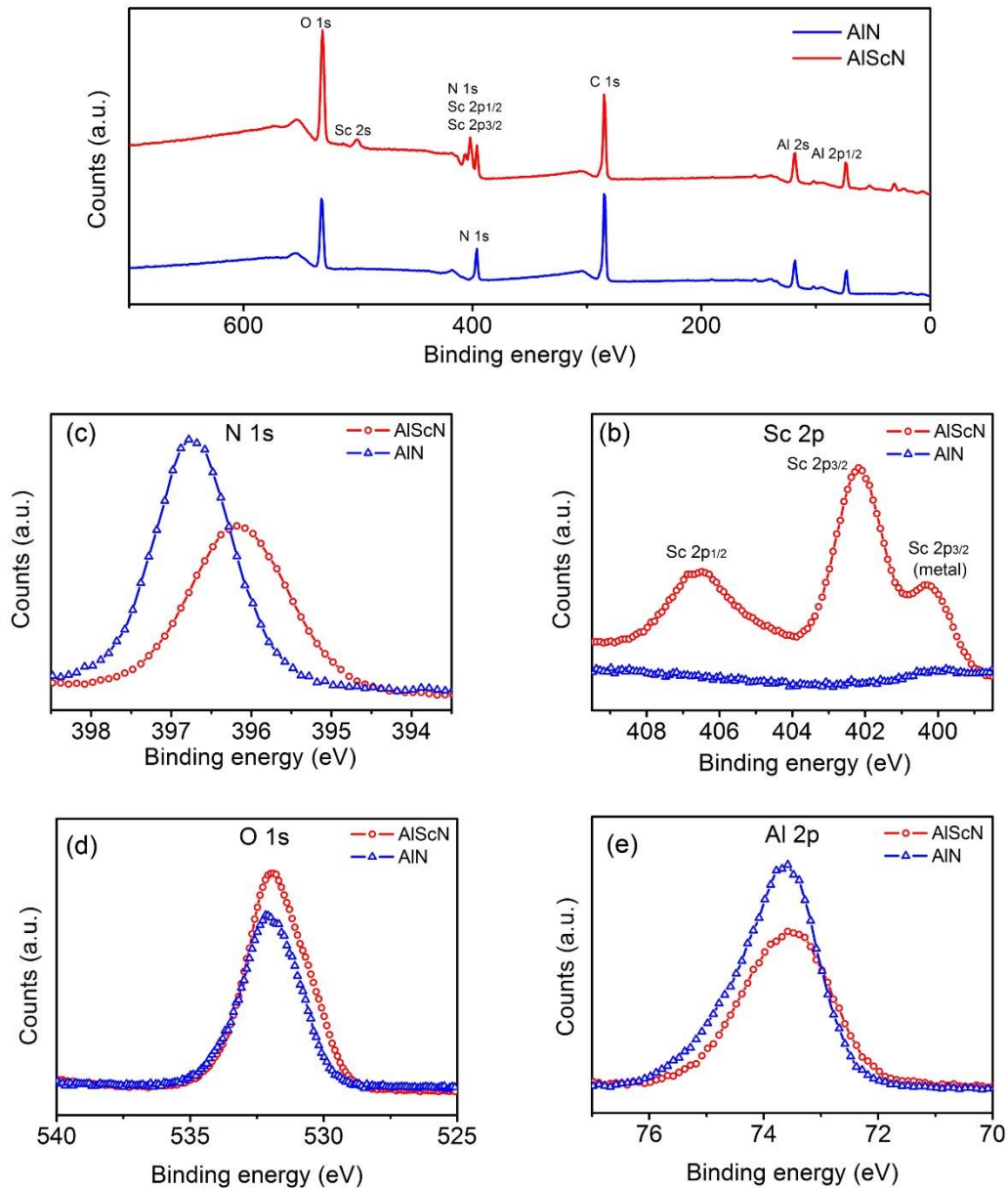


Fig. 1 Comparison of XPS survey scans of AlN and AlScN thin films with binding energy range of 0-800 eV (a). The main peaks are identified and the presence of Sc is evident from the Sc 2p peaks with a binding energy of ~ 400 eV. And the detailed scanning of main peaks of AlScN and AlN: Sc 2p peaks around 400 eV (a), N 1s (b), O 1s (c) and Al 2p (d).

Doping AlN with scandium results in a series of Sc 2p peaks appear at around 400-410 eV. The Sc 2p peak shown in Fig. 1(b) consists of two distinct sub-peaks. According to literature,³⁶ the first peak from ~400.3 eV to 403.0 eV is related to Sc 2p_{3/2}. The peak at ~400.3 eV is associated with metallic scandium. The large peak positioned at ~402.2 eV is a composite peak with the combination of both Sc 2p_{3/2} of Sc-N and Sc-O bond,^{36,37} implying that part of Sc elements substituting Al atoms form covalent bonds with N and O. Similarly, the broad peak centered at ~406.5 eV is a composite peak of Sc 2p_{1/2} binding energy, with two main components, one of them is metallic Sc 2p_{1/2}, and another one is a combined ones from both Sc 2p_{1/2} of Sc-N and Sc-O bond.³⁶ The N 1s peak shown in Fig. 1(c) demonstrates a ~1 eV blue-shift of binding energy after doping with scandium which is due to combination of Sc-N and Al-N bonds.³⁷ Figs. 1(d) and 1(e) illustrate slight blue-shift of the binding energy for the O 1s and Al 2p peak, possibly caused by disturbance of the Sc doping. The oxygen peak is mainly related to the molecule adsorbed on the surface and they are less affected by scandium doping. On the other hand, incorporation of Sc has led to a minor shift of Al to the lower energy side, which indicates that the involvement of the Sc atoms slightly change the ratio of Al-O and Al-N binding.

SEM micrographs in Figs. 3(a) and 3(b) show the fine microstructures of both the films and a columnar microstructure can be clearly observed from the cross-sectional view in Fig. 3(c). The surface morphology of AlScN presents rougher and a bit irregular compare with pure AlN sample, indicating that the heavy scandium doping will cause uniform growth and distribution in crystal structures. XRD results reported in our previous work showed a good (0002) texture for both the samples.³¹ Smooth surfaces and columnar microstructures with a (0002) texture are beneficial for piezoelectric properties and acoustic wave device applications and can reduce scattering effects and wave propagation loss.

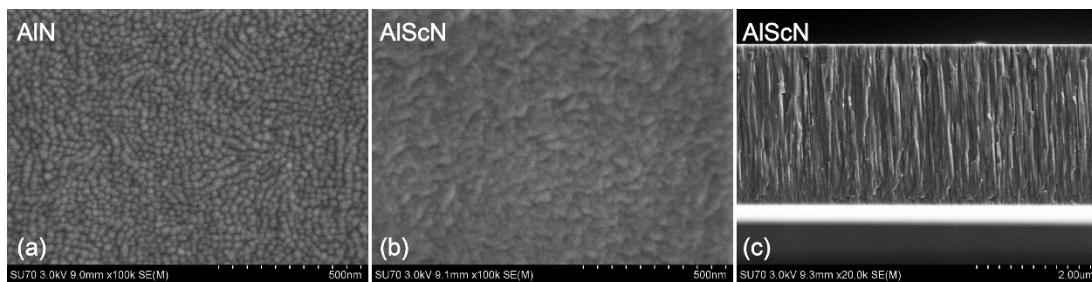


Fig. 2 SEM image: top view of AlN (a), AlScN (b) thin film and cross sectional view of AlScN (c) sample.

Hardness and Young's modulus values for these two different types of samples are plotted in Fig. 3, as a function of contact depth. As commented in ref. 38, the nanoindentation results would be significantly affected by surface roughness when the penetration is below five times the surface roughness.³⁸ Therefore, the indentation results for very small penetration (less than 20nm) were discarded. There are several methods that enable determining the Young's modulus and hardness of thin coatings based on nanoindentation tests.^{25,39-43} Among these, the extrapolation of measured elastic modulus and hardness values of the coated systems to zero contact depth based on ISO14577 standard

is simple and effective³⁹ and this will be adopted in study here. As shown in Fig. 3, the values of Young's modulus and hardness of AlN film are ~209 GPa and 16.4 GPa respectively, which are higher than what were reported in ref. 44. This may suggest that the AlN films produced in this work have denser structure compared to the films reported.⁴⁰ AlN is one of the hardest materials with the Young's modulus of ~345 GPa. The value of ~210 GPa obtained in this work is much smaller than the one for bulk AlN material probably due to the unoptimized deposition condition, and thin film and polycrystalline nature, but much larger than 110.4 GPa reported in ref. 44 for which the deposition process and films may not be optimized at all.

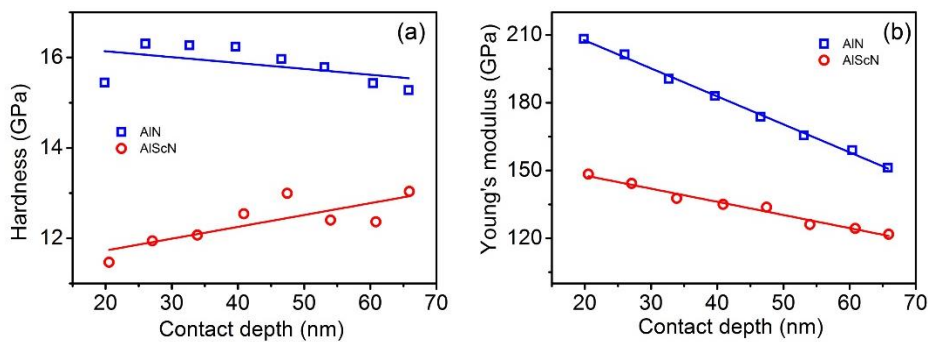


Fig.3 Comparison of the mechanical property: hardness (a) and Young's modulus (b). The data was obtained from nanoindentation tests.

The Young's modulus and hardness of the Sc doped AlN film are 149.4 GPa and 11.5 GPa, respectively, much lower than those of AlN. Many theoretical researches indicate there is a softening effect of the Sc doping,^{27,39} but may depend on the Sc concentration. Yang *et al* reported that at low Sc doping concentration, Sc may cause the Sc-N phase forming and restrict the growth of AlN grains.⁴⁰ The new Sc-N phase can act as a barrier to dislocation propagation which will enhance the hardness. However, further doping may lead to grain size decreased, and the grain boundary shearing begins to dominate the dislocation motion and the hardness will then decrease.^{44,45} The change trend of hardness with measurement depth for both the thin films is different, and is believed to be correlated to the hardness of Si substrate which is about 13 GPa, higher than that of AlScN, but lower than that of AlN. With the increase in measurement depth, the effect of substrate becomes stronger, leading to opposite change of the hardness with depth measured.

Comparison of transmission spectra (S_{21}) of AlN and AlScN SAW devices is displayed in Fig. 4. It can be seen that after doping with scandium, the insertion loss of the AlScN film is significantly increased from ~-40 dB to ~-30 dB, and the peak amplitude is increased from ~17 dB to ~20 dB, implying that more acoustic energy has been transmitted, which could be beneficial for sensing, actuation and microfluidic applications. The resonant frequency also decreases slightly from 240 MHz for AlN SAW to 236.6 MHz for the Sc doped AlScN films. This corresponds to a decrease of the phase

velocity from ~4800 m/s for AlN SAW to ~4730 m/s for the AlScN SAW. This is mainly due to the elastic softening after doping with Sc and change of crystal structure, consistent with the reduction of the mechanical strength obtained by Nanoindentation shown above. The K^2 values were calculated using the following equation:

$$K^2 = \frac{\pi G_m(f_r)}{4NB_s(f_r)}$$

where N is the finger pairs, $G_m(f_r)$ and $B_s(f_r)$ are the motional conductance and static susceptance at the resonant frequency, f_r , respectively, both the values were obtained from the Smith chart. K^2 values are shown in the inset of Fig. 4. There is more than 400% increase of the K^2 value after doing with 27% scandium for the AlN SAW devices. The increase of K^2 value depends on the normalized thickness of the active layer, but all more than 300% larger compared to that of AlN SAW as detailed in our previous work.³¹ The great increase of the coupling coefficient is believed to be mainly caused by the significantly improved piezoelectric coefficient from elastic softening. This will significantly improve device performance, beneficiary for sensor, actuator and microfluidic applications.³¹

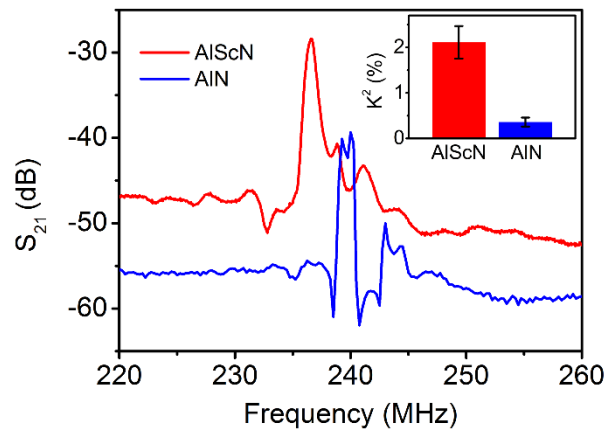


Fig. 4 Comparison of transmission spectra (S_{21}) and K^2 values for AlN and AlScN devices with a wavelength of 20 μm .

To test this, we studied the acoustic wave based microfluidic phenomenon as an example for both the AlN and AlScN based SAW. Acoustic streaming can be easily obtained as shown in Fig. 5(a). The streaming was initially only confined in the local wave interaction areas in the droplet, especially for large scale droplets. This is because for such a high frequency SAW, the attenuation length is much shorter, and energy is dissipated easily in the front part of liquid droplet.^{2,14} Figs. 5(b) and 5(c) compare the threshold powers for streaming and streaming velocities for the microfluidics tests based on the AlN and AlScN devices, respectively. The threshold power is a critical parameter for microfluidic applications, and a lower threshold power means that it is easier for the device to actuate liquid, indicating a higher efficiency and lower power dissipation. Fig. 5(b) demonstrates that with Sc doping,

the threshold power of AlScN devices for streaming is ~40% of that of AlN ones. This makes the AlScN SAW device to produce much higher acoustic streaming velocity than that of AlN at the same power. For instance, a 9 cm/s streaming velocity was obtained from AlScN SAW at an RF power of ~1.85 W, more than double of those (~4 cm/s) delivered by AlN SAW devices at the similar RF power.^{9,14} On the other hand, despite the much higher working frequency (~240 MHz), the AlN devices show a comparable threshold power value for streaming with those reported in literature (80.3 MHz AlN SAW).²⁰

We also studied the pumping velocities and threshold power of water droplet transportation for these two types of devices with the results shown in Fig. 5(d) and 5(e) respectively. Similar to acoustic streaming phenomenon, the AlScN SAW devices present a much lower threshold power needed for pumping the droplet, and also achieve a higher velocity of pumping than those of the pure AlN SAW devices. With an RF power of 19.45 W, the AlScN SAW devices can achieve a droplet velocity of around 4 mm/s, which is 3 times higher than that of the AlN devices. Clearly, the enhancement of SAW microfluidic performance has been achieved by using scandium doped AlN SAW devices.

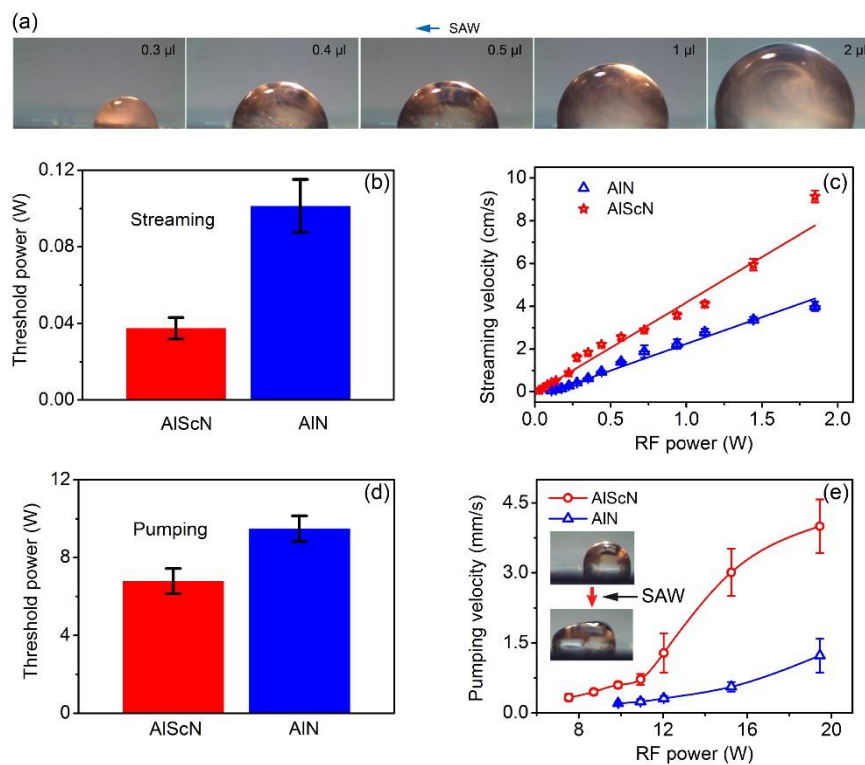


Fig. 5 Photos of steaming phenomenon of AlScN based SAW devices with different droplet volumes (a), comparison of their threshold powers (b)(d), streaming velocities (c) and pumping velocities between AlN and AlScN SAW devices. The droplet volume was 2 μL for the comparison work.

Temperature coefficient is an important value to estimate temperature stability of SAW devices, and increase in device temperature could shift the wave frequency, which could influence the resonant

frequency, hence the performance of sensors, actuators and microfluidic devices during operation. Fig. 6 shows the frequency shift as a function of temperature, and the TCF values were calculated to be \sim 31.0 ppm/K and \sim 32.9 ppm/K for AlN and AlScN SAW device, respectively, that are consistent with those reported for the AlN SAW devices.²³ Significant doping with Sc in the AlN film only increases the TCF value slightly, but the trend is consistent with the reduced Young's modulus and hardness values for the AlScN film as shown above. It is a common knowledge that softer materials have higher thermal expansion coefficient. It may be good to explain how this would affect the stability or reliability of the device at high temperature. For applications, especially microfluidics with high RF power used, temperature rise is quite common because of the strong lattice vibration and acoustic heating effect. A low TCF value with an excellent linearity will enable the AlScN based SAW devices to be employed for various sensing, actuation and microfluidic applications with better control and reliable results.

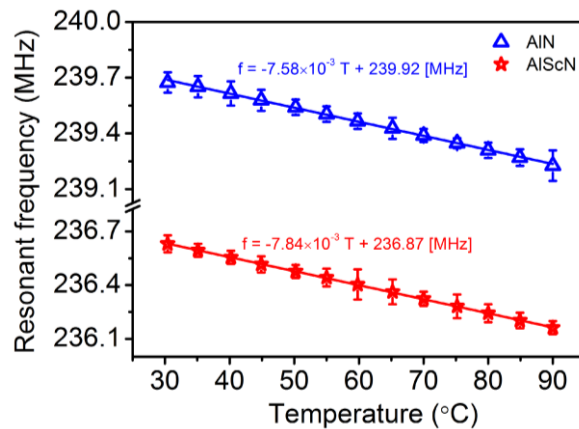


Fig. 6 Resonant frequency as a function of temperature for both AlN and AlScN devices, the temperature region is 30-90°C.

4. Conclusions

In summary, both the AlN and AlScN thin films showed a smooth surface morphology and a columnar microstructure perpendicular to the substrate surface and good (0002) film textures. AlScN based SAW devices demonstrated higher electromechanical coefficients (\sim 2%) compared with those based on AlN films ($<$ 1%). With high doping of scandium, significant softening effects (i.e. drop in Young's modulus and hardness) have been observed compared to pure AlN, which is correlated to the increase in the TCF and decrease in the phase velocity (resonant frequency). As a consequence, the AlScN SAW devices showed a lower power threshold as well as a higher velocity for both streaming and pumping, two major microfluidic functions, and demonstrated that scandium doping improved the acoustofluidic performance significantly. In addition, the nanoindentation results also suggest that deposition conditions may need further optimization to improve the microstructure of the coatings and thus the performance of the devices.

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